

04-15-05

IFW



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/779,563  
Filing Date: February 16, 2004  
Applicant: Yoshiro Iwasa  
Group Art Unit: Unknown  
Examiner: Unknown  
Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE,  
METHOD FOR MANUFACTURING SEMICONDUCTOR  
DEVICE, AND SEMICONDUCTOR DEVICE  
Attorney Docket: 9319S-000666

---

U.S. Patent and Trademark Office  
Mail Stop: **Duplicates**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Reply to NOTICE UNDER 37 CFR 1.251 – Pending Application

Sir:

In response to the above-identified notice mailed April 7, 2005, Applicant has reviewed its files and states that no Information Disclosure Statement was filed on 06/16/04. An Information Disclosure Statement was, however, mailed to the PTO along with the original application papers on February 16, 2004. A duplicate copy of that IDS and the references are enclosed.

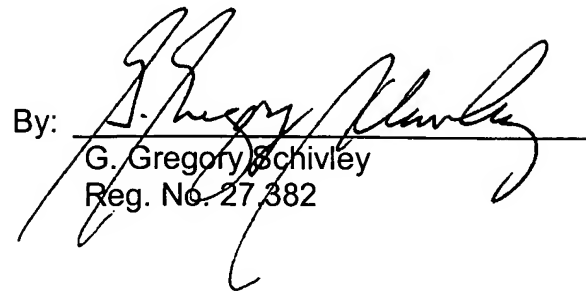
EV 570 162 508 US



Favorable consideration of this application is respectfully requested.

Respectfully submitted,

Dated: April 14, 2005

By:   
G. Gregory Schivley  
Reg. No. 27,382

HARNESS, DICKEY & PIERCE, P.L.C.  
P.O. Box 828  
Bloomfield Hills, Michigan 48303  
(248) 641-1600

GGs/slm

